MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

CERAMIC DIP 28, 48.01x15.5
CASE 125BC
ISSUE O

DATE 30 JUL 2014

NOTES:
1. CODE IS MARKED ON CERAMIC.
2. COVER GLASS IS VISUALLY ALIGNED OVER DIE — NO GUARANTEE OF LOCATION ACCURACY.

Dimensions in: Inches [mm]

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1. CENTER DIE VERTICALLY ON SILVER D/A PAD.
2. CENTER DIE HORIZONTALLY WITH RESPECT TO OUTER EDGES OF PACKAGE BOND FINGERS. IF DIE IS LONGER OR SHORTER THAN OUTER EDGES OF BOND FINGERS THEN SPLIT THE DIFFERENCE BETWEEN THE TWO ENDS SO THAT THE DIE IS CENTERED IN THE CAVITY.
3. (X, Y) COORDINATES SHOWN ARE FOR MEASUREMENT VERIFICATION AND ARE RELATIVE TO THE DATUMS THROUGH THE CENTER OF THE PACKAGE HOLES.
4. MONO SENSOR IS LOCATED IN THE SAME LOCATION OF THE PACKAGE AND HAS THE SAME TARGETS AND FIDUCIALS BUT NO COLOR CFA.

COLOR SENSOR

NOTE: CENTER HORIZONTALLY OR SILVER PAD TO OUTER EDGES OF PACKAGE BOND FINGERS. IF DIE IS LONGER OR SHORTER THAN OUTER EDGES OF BOND FINGERS THEN SPLIT THE DIFFERENCE BETWEEN THE TWO ENDS. WHOS THE CENTER OF THE Package AND HAS THE SAME Targets AND FIDUCIALS BUT NO COLOR CFA.